## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1222337	(semiconductor die chip dice ic electronic component (integrated adj circuit) flichip (flip adj chip)) with (substrate carrier board ((printed circuit\$2 metal wiring mount\$3) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/24 06:34
L2	62031	1 same (flipchip (flip adj chip) ball bump)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/24 06:33
L3	446626	(bend\$4 flex flexibl\$5 slant groove dip curv\$3 recess\$4) with (substrate carrier board ((printed circuit\$2 metal wiring mount\$3) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/24 08:01
L4 -	446626	3 same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/24 06:36
L5	7361	3 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ,	<sup>k</sup> ON	2006/06/24 06:36
L6	5145	(module packag\$3) and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON ,	2006/06/24 06:37
L7 -	3522	(metal cuw mo cumo ((copper cu) adj (clad invar mo)) invar) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/24 08:02
L8 -	3583	(metal cuw mo cumo ((copper cu) adj (clad invar mo)) invar steel stainless) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/06/24 06:38

## **EAST Search History**

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L9	1931	(organic dielectric) and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/06/24 08:03
L10	60884	cavity with (substrate carrier board ((printed circuit\$2 metal wiring mount\$3) adj4 board))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ,	ON h	2006/06/24 08:02
L11 -	2004	10 same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/2 <u>4</u> 08 <u>:</u> 02
L12	1858	11 not 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/24 08:02
L13	1084	(metal cuw mo cumo ((copper cu) adj (clad invar mo)) invar) and 12	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/06/24 08:02
L14	488	(organic dielectric) and 13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/06/24 08:03